

PMBTA42

300 V, 100 mA NPN high-voltage transistor

Rev. 05 — 12 December 2008

Product data sheet

1. Product profile

1.1 General description

NPN high-voltage transistor in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package.

PNP complement: PMBTA92.

1.2 Features

- High voltage (max. 300 V)

1.3 Applications

- Telephony and professional communication equipment

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CE0}	collector-emitter voltage	open base	-	-	300	V
I_C	collector current		-	-	100	mA
h_{FE}	DC current gain	$V_{CE} = 10\text{ V}$				
		$I_C = 1\text{ mA}$	25	-	-	
		$I_C = 10\text{ mA}$	40	-	-	
		$I_C = 30\text{ mA}$	40	-	-	

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	base		
2	emitter		
3	collector		

sym021

3. Ordering information

Table 3. Ordering information

Type number ^[1]	Package		
	Name	Description	Version
PMBTA42	-	plastic surface-mounted package; 3 leads	SOT23
PMBTA42/DG			

[1] /DG: halogen-free

4. Marking

Table 4. Marking codes

Type number ^[1]	Marking code ^[2]
PMBTA42	*1D
PMBTA42/DG	*BV

[1] /DG: halogen-free

[2] * = -: made in Hong Kong

* = p: made in Hong Kong

* = t: made in Malaysia

* = W: made in China

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter	-	300	V
V_{CEO}	collector-emitter voltage	open base	-	300	V
V_{EBO}	emitter-base voltage	open collector	-	6	V
I_C	collector current		-	100	mA
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms	-	200	mA
I_{BM}	peak base current	single pulse; $t_p \leq 1$ ms	-	100	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	^[1] -	250	mW
T_j	junction temperature		-	150	°C
T_{amb}	ambient temperature		-65	+150	°C
T_{stg}	storage temperature		-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	500	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

7. Characteristics

Table 7. Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{CBO}	collector-base cut-off current	$V_{CB} = 200\text{ V}; I_E = 0\text{ A}$	-	-	100	nA
I_{EBO}	emitter-base cut-off current	$V_{EB} = 6\text{ V}; I_C = 0\text{ A}$	-	-	100	nA
h_{FE}	DC current gain	$V_{CE} = 10\text{ V}$				
		$I_C = 1\text{ mA}$	25	-	-	
		$I_C = 10\text{ mA}$	40	-	-	
		$I_C = 30\text{ mA}$	40	-	-	
V_{CEsat}	collector-emitter saturation voltage	$I_C = 20\text{ mA}; I_B = 2\text{ mA}$	-	-	500	mV
V_{BEsat}	base-emitter saturation voltage	$I_C = 20\text{ mA}; I_B = 2\text{ mA}$	-	-	900	mV
C_{re}	feedback capacitance	$V_{CB} = 20\text{ V}; I_C = i_c = 0\text{ A};$ $f = 1\text{ MHz}$	-	-	3	pF
f_T	transition frequency	$V_{CE} = 20\text{ V}; I_C = 10\text{ mA};$ $f = 100\text{ MHz}$	50	-	-	MHz

8. Package outline

Plastic surface-mounted package; 3 leads

SOT23

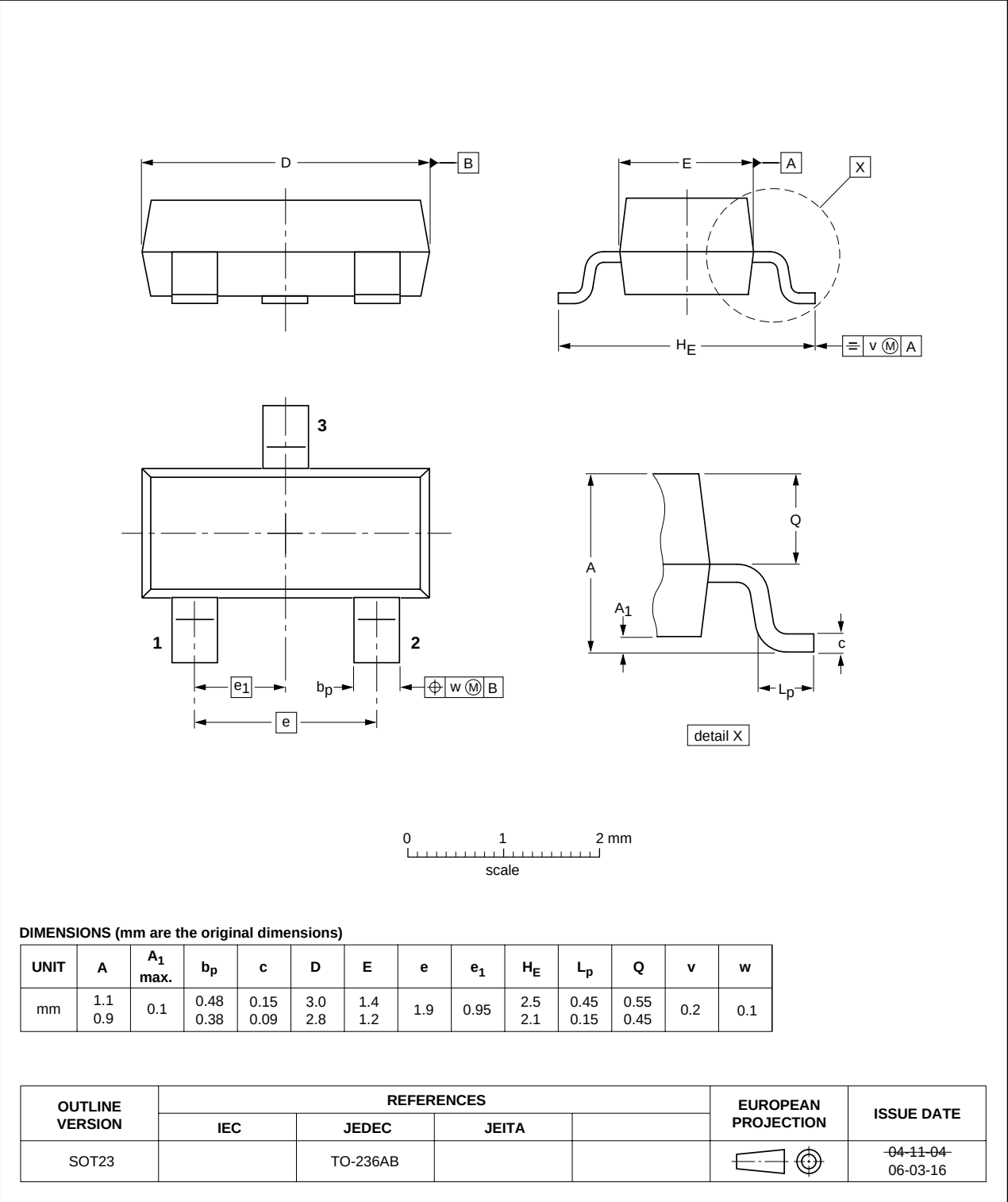


Fig 1. Package outline SOT23 (TO-236AB)

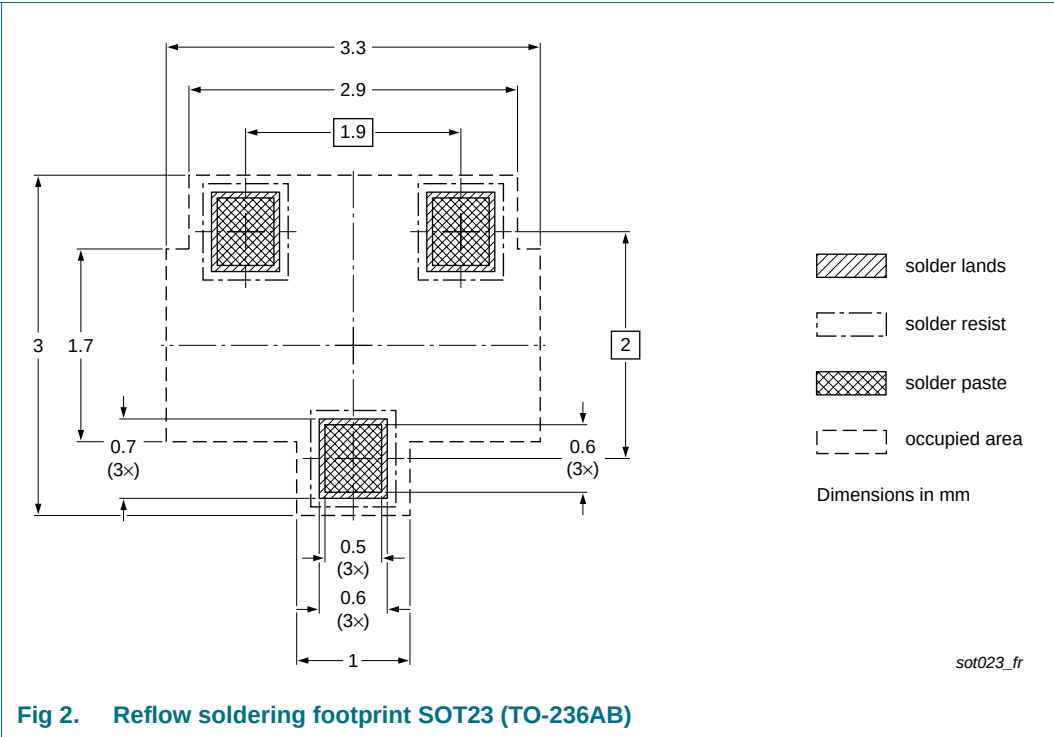
9. Packing information

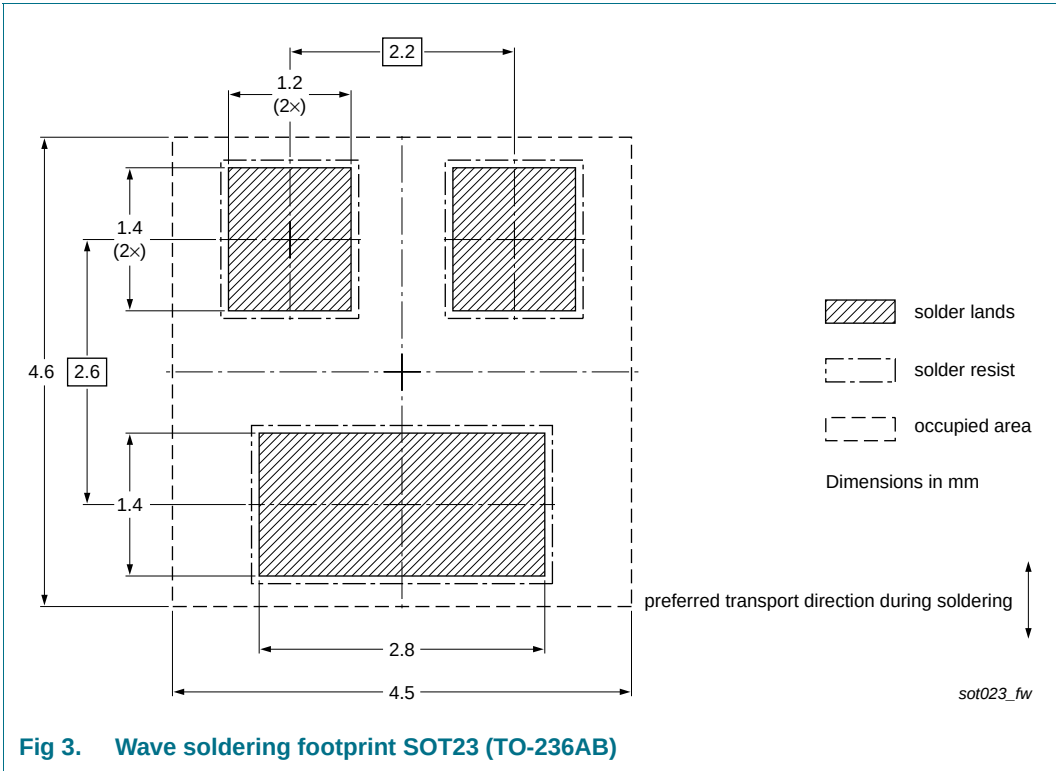
Table 8. Packing methods
The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity	
			3000	10000
PMBTA42	SOT23	4 mm pitch, 8 mm tape and reel	-215	-235
PMBTA42/DG				

[1] For further information and the availability of packing methods, see [Section 13](#).
[2] /DG: halogen-free

10. Soldering





11. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMBTA42_5	20081212	Product data sheet	-	PMBTA42_4
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Type number PMBTA42/DG added • Table 4 “Marking codes”: enhanced • Section 12 “Legal information”: updated			
PMBTA42_4	20040122	Product specification	-	PMBTA42_3
PMBTA42_3	19990422	Product specification	-	PMBTA42_43_CNV_2

12. Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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